

Electronic Patent Application Fee Transmittal

| | |
|---|--|
| Application Number: | 10581928 |
| Filing Date: | 07-Jun-2006 |
| Title of Invention: | Thermosetting Resin Composition, Resin Sheet and Resin Sheet for Insulated Substrate |
| First Named Inventor/Applicant Name: | Koichi Shibayama |
| Filer: | Lee Cheng/Maki Huffman |
| Attorney Docket Number: | MIY-0212 |

Filed as Large Entity

U.S. National Stage under 35 USC 371 Filing Fees

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|--|----------|----------|--------|----------------------|
| Basic Filing: | | | | |
| Pages: | | | | |
| Claims: | | | | |
| Miscellaneous-Filing: | | | | |
| Petition: | | | | |
| Patent-Appeals-and-Interference: | | | | |
| Post-Allowance-and-Post-Issuance: | | | | |
| Extension-of-Time: | | | | |
| Extension - 2 months with \$0 paid | 1252 | 1 | 490 | 490 |

| Description | Fee Code | Quantity | Amount | Sub-Total in USD(\$) |
|-------------------|----------|----------|--------|----------------------|
| Miscellaneous: | | | | |
| Total in USD (\$) | | | | 490 |